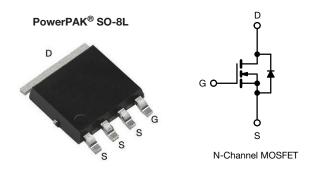
Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

## **E Series Power MOSFET**



PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	65	50			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.208			
Q <sub>g</sub> max. (nC)	2	3			
Q <sub>gs</sub> (nC)	4	1			
Q <sub>gd</sub> (nC)	6	3			
Configuration	Sin	Single			

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

## **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Load (Dh) free and helegan free	SiHJ240N60E-T1-GE3
Lead (Pb)-free and halogen-free	SiHJ240N60E-T2-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			$V_{DS}$	600	V
Gate-source voltage			$V_{GS}$	± 30	7 °
Continuous drain surrent (T. 150 °C)	V at 10 V	T <sub>C</sub> = 25 °C		12	А
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	7	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	30	
Linear derating factor				0.63	W/°C
Single pulse avalanche energy b			E <sub>AS</sub>	81	mJ
Maximum power dissipation			P <sub>D</sub>	89	W
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope $T_J = 125  ^{\circ}\text{C}$			dv/dt	100	V/ns
Reverse diode dv/dt <sup>c</sup>				28	V/IIS

#### **Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 2.4 A
- c.  $I_{SD} \le I_D$ , di/dt = 100 A/µs, starting  $T_J = 25~^{\circ}C$



# Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	52	65	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	1.0 1.4		C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.63	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	- V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Cata assuma lagicara		,	V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 30 V		-	± 1	μΑ
Zoro goto voltago drain ourrent		V <sub>DS</sub> =	= 600 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 5.5 A	-	0.208	0.240	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> :	= 20 V, I <sub>D</sub> = 5.5 A	-	4	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	783	-	
Output capacitance	C <sub>oss</sub>	] ,	$V_{DS} = 100 V$	-	50	-	
Reverse transfer capacitance	C <sub>rss</sub>		f = 1 MHz	-	5	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	32	-	pF -
Effective output capacitance, time related <sup>b</sup>	$C_{o(tr)}$			-	187	-	
Total gate charge	Qg			-	15	23	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 5.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	4	-	nC
Gate-drain charge	$Q_{gd}$			-	6	-	
Turn-on delay time	t <sub>d(on)</sub>			1	15	30	
Rise time	t <sub>r</sub>	$V_{DD} = 480 \text{ V}, I_D = 5.5 \text{ A},$		ı	14	28	ne
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	= 10 V, $R_g$ = 9.1 $\Omega$	ī	26	52	ns
Fall time	t <sub>f</sub>			ı	14	28	
Gate input resistance	$R_g$	f = 1	MHz, open drain	0.8	1.5	3.0	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	showing the	MOSFET symbol showing the		-	12	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	30	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 5.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	209	418	ns
Reverse recovery charge	Q <sub>rr</sub>		5 °C, I <sub>F</sub> = I <sub>S</sub> = 5.5 A,	-	2.1	4.2	μC
Reverse recovery current	I <sub>RRM</sub>	ai/at = 1	100 A/ $\mu$ s, V <sub>R</sub> = 25 V	_	18	-	Α

### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

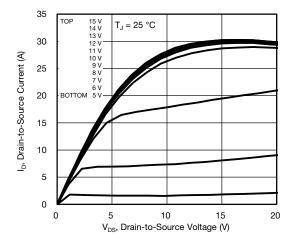


Fig. 1 - Typical Output Characteristics

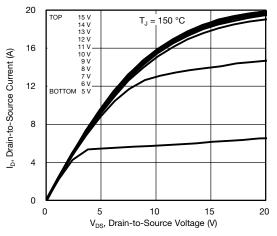


Fig. 2 - Typical Output Characteristics

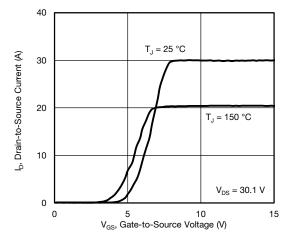


Fig. 3 - Typical Transfer Characteristics

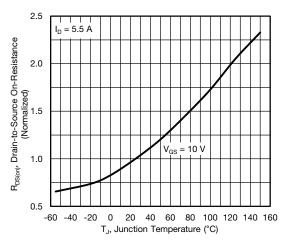


Fig. 4 - Normalized On-Resistance vs. Temperature

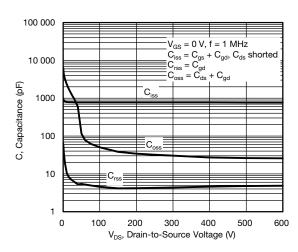


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

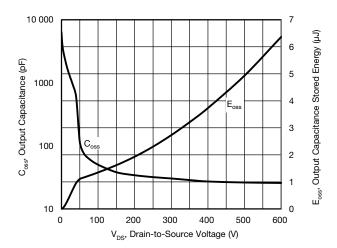


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



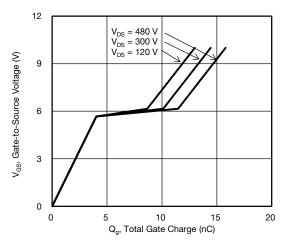


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

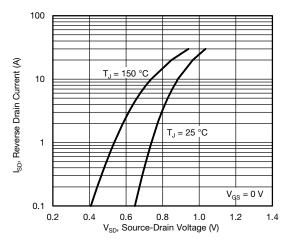


Fig. 8 - Typical Source-Drain Diode Forward Voltage

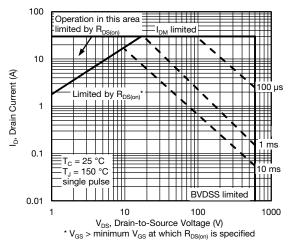


Fig. 9 - Maximum Safe Operating Area

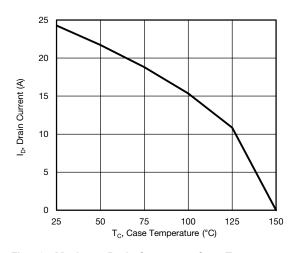


Fig. 10 - Maximum Drain Current vs. Case Temperature

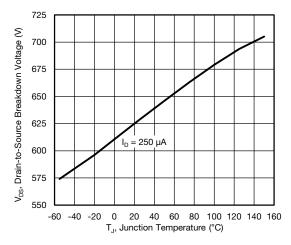


Fig. 11 - Temperature vs. Drain-to-Source Voltage



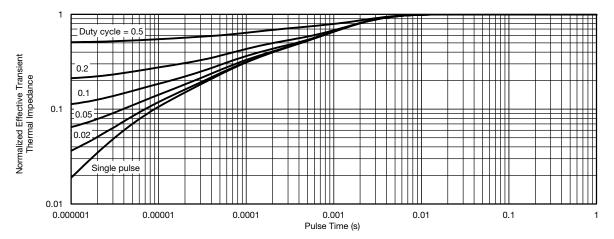


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

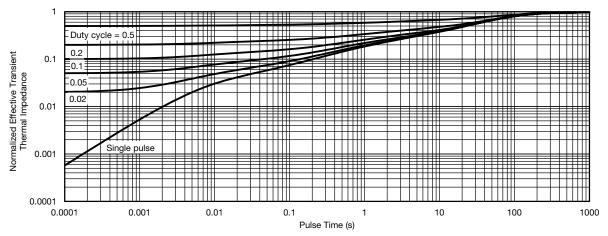


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

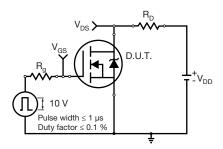


Fig. 14 - Switching Time Test Circuit

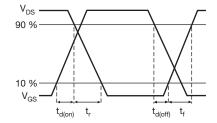


Fig. 15 - Switching Time Waveforms



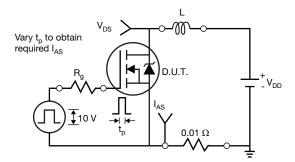


Fig. 16 - Unclamped Inductive Test Circuit

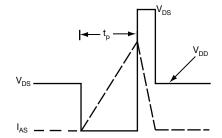


Fig. 17 - Unclamped Inductive Waveforms

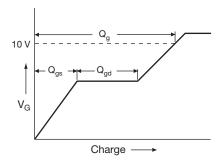


Fig. 18 - Basic Gate Charge Waveform

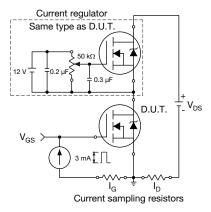
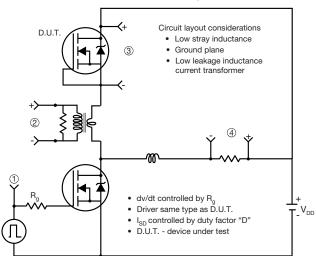


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



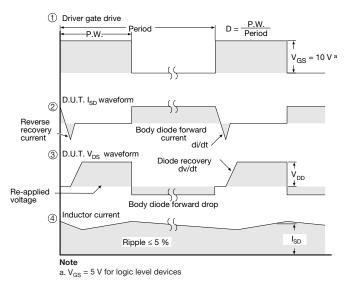
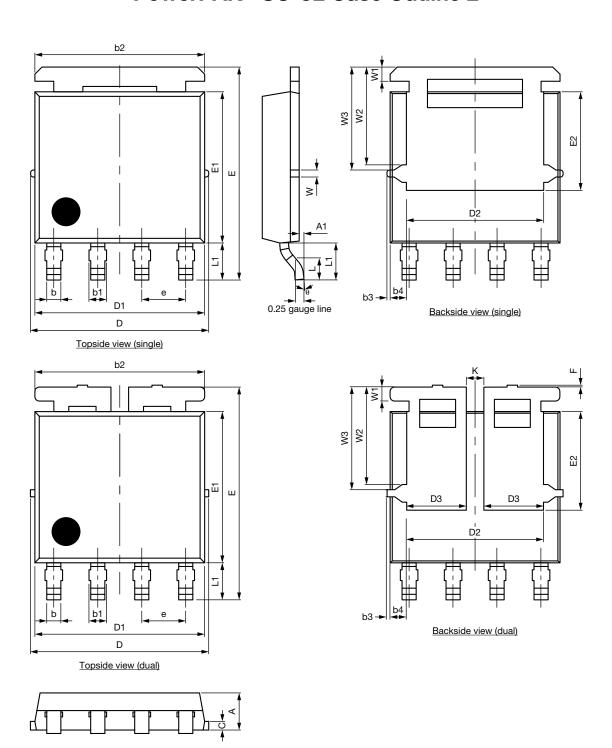


Fig. 20 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?92102">www.vishay.com/ppg?92102</a>.



# PowerPAK® SO-8L Case Outline 2



Revision: 01-Nov-2021 1 Document Number: 66934



Vishay Siliconix

DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	C. MIN. NOM. N			
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23		0.009				
W1	0.41		0.016				
W2	2.82		0.111				
W3	2.96			0.117			
θ	0°	-	10°	0°	-	10°	

ECN: C21-1498-Rev. C, 01-Nov-2021

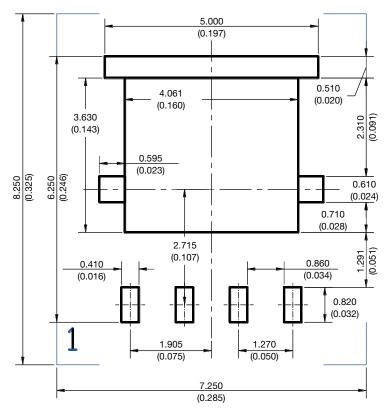
DWG: 6044

### Note

• Millimeters will govern



## RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

# **Legal Disclaimer Notice**



Vishay

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